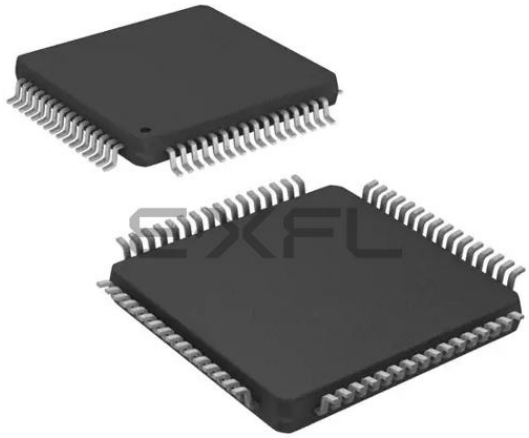
Microchip Technology - DSPIC33FJ64MC706AT-I/PT Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

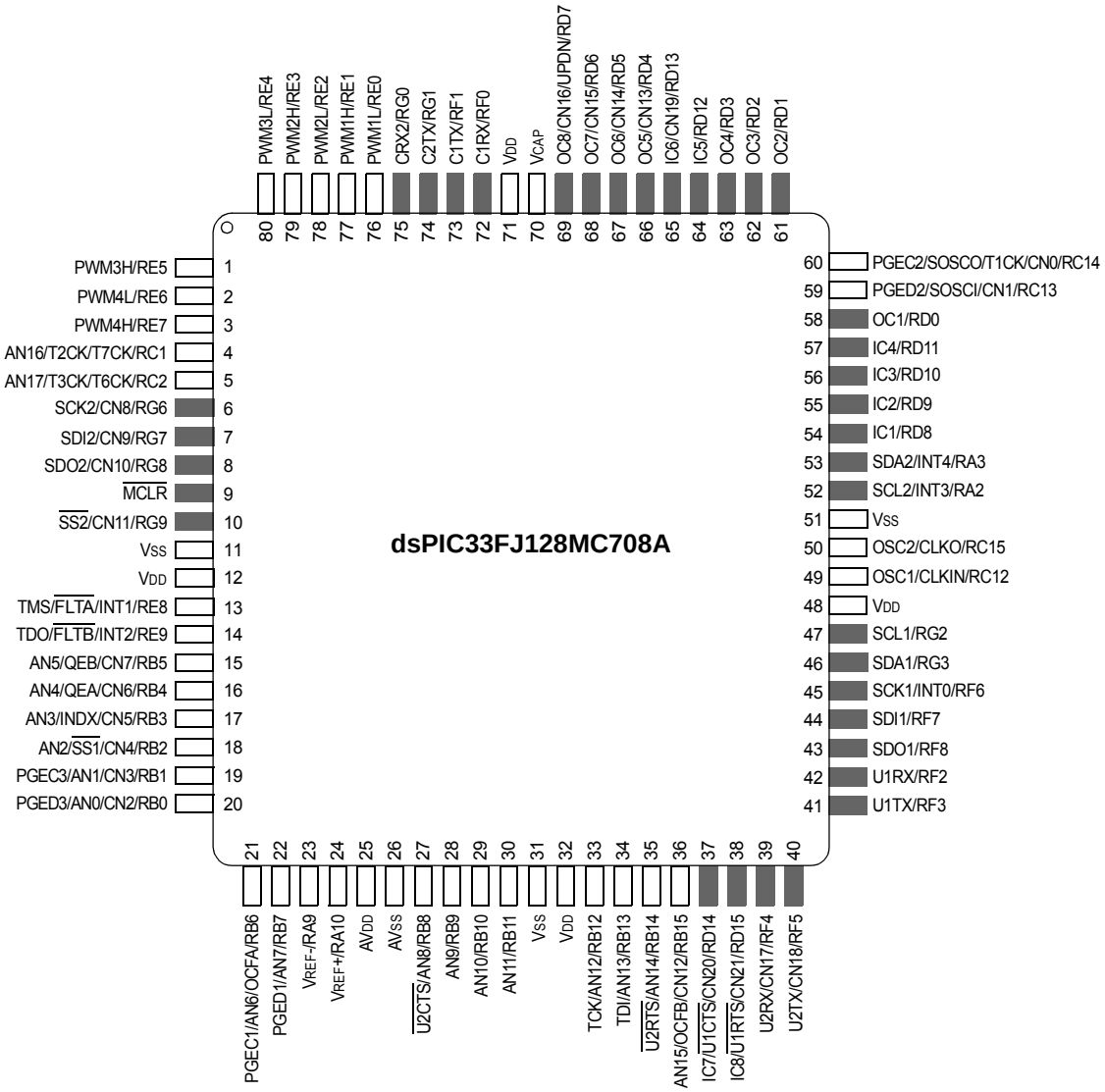
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, QEI, WDT
Number of I/O	53
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj64mc706at-i-pt

Pin Diagrams (Continued)

80-Pin TQFP

■ = Pins are up to 5V tolerant



REGISTER 3-1: SR: CPU STATUS REGISTER (CONTINUED)

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits(2)
111 = CPU interrupt priority level is 7 (15), user interrupts disabled
110 = CPU interrupt priority level is 6 (14)
101 = CPU interrupt priority level is 5 (13)
100 = CPU interrupt priority level is 4 (12)
011 = CPU interrupt priority level is 3 (11)
010 = CPU interrupt priority level is 2 (10)
001 = CPU interrupt priority level is 1 (9)
000 = CPU interrupt priority level is 0 (8)

bit 4 **RA:** REPEAT Loop Active bit
1 = REPEAT loop in progress
0 = REPEAT loop not in progress

bit 3 **N:** MCU ALU Negative bit
1 = Result was negative
0 = Result was non-negative (zero or positive)

bit 2 **OV:** MCU ALU Overflow bit
This bit is used for signed arithmetic (2's complement). It indicates an overflow of the magnitude that causes the sign bit to change state.
1 = Overflow occurred for signed arithmetic (in this arithmetic operation)
0 = No overflow occurred

bit 1 **Z:** MCU ALU Zero bit
1 = An operation which affects the Z bit has set it at some time in the past
0 = The most recent operation which affects the Z bit has cleared it (i.e., a non-zero result)

bit 0 **C:** MCU ALU Carry/$\overline{\text{Borrow}}$ bit
1 = A carry-out from the Most Significant bit of the result occurred
0 = No carry-out from the Most Significant bit of the result occurred

Note 1: This bit may be read or cleared (not set).
2: The IPL<2:0> bits are concatenated with the IPL<3> bit (CORCON<3>) to form the CPU interrupt priority level. The value in parentheses indicates the IPL if IPL<3> = 1. User interrupts are disabled when IPL<3> = 1.
3: The IPL<2:0> Status bits are read only when NSTDIS = 1 (INTCON1<15>).
4: This bit may be read or cleared (not set). Clearing this bit will clear SA and SB.

5.0 FLASH PROGRAM MEMORY

Note 1: This data sheet summarizes the features of the dsPIC33FJXXXMCX06A/X08A/X10A family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 5. "Flash Programming"** (DS70191) in the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33FJXXXMCX06A/X08A/X10A devices contain internal Flash program memory for storing and executing application code. The memory is readable, writable and erasable during normal operation over the entire VDD range.

Flash memory can be programmed in two ways:

1. In-Circuit Serial Programming™ (ICSP™) programming capability
2. Run-Time Self-Programming (RTSP)

ICSP allows a dsPIC33FJXXXMCX06A/X08A/X10A device to be serially programmed while in the end application circuit. This is simply done with two lines for programming clock and programming data (one of the alternate programming pin pairs: PGECx/PGEDx), and three other lines for power (VDD), ground (VSS) and Master Clear (MCLR). This allows customers to manufacture boards with unprogrammed devices and then program the digital signal controller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

RTSP is accomplished using TBLRD (table read) and TBLWT (table write) instructions. With RTSP, the user can write program memory data by blocks (or 'rows') of 64 instructions (192 bytes) at a time or by single program memory word; the user can erase program memory in blocks or 'pages' of 512 instructions (1536 bytes) at a time.

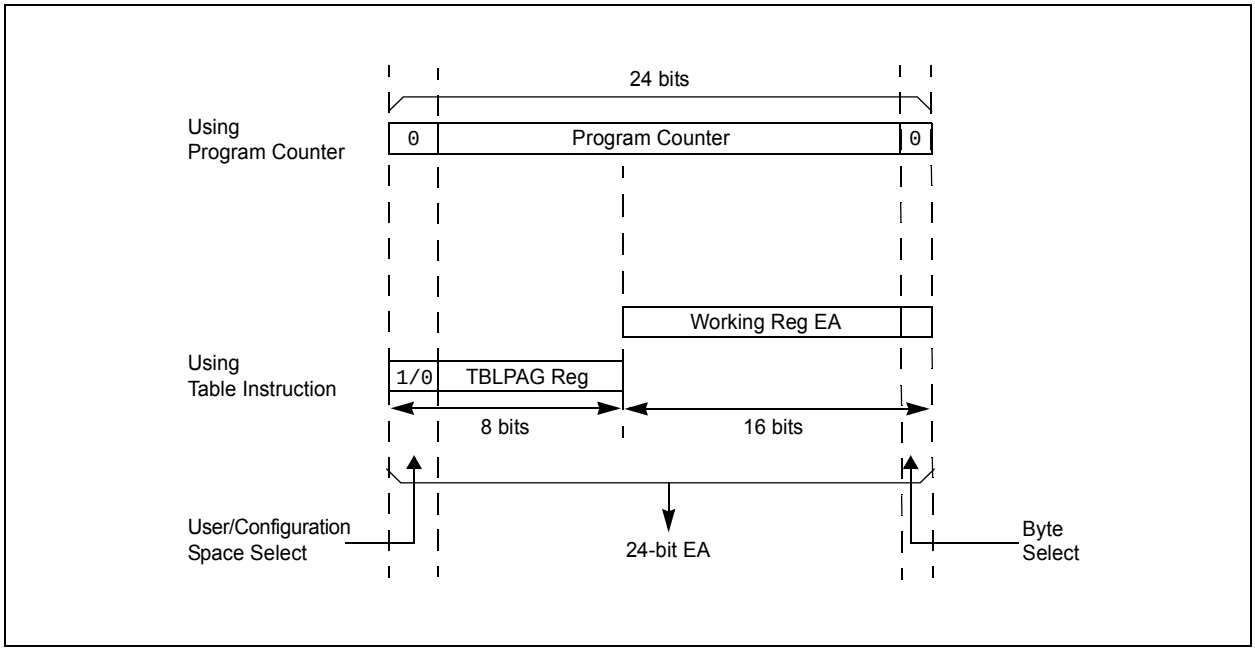
5.1 Table Instructions and Flash Programming

Regardless of the method used, all programming of Flash memory is done with the table read and table write instructions. These allow direct read and write access to the program memory space from the data memory while the device is in normal operating mode. The 24-bit target address in the program memory is formed using bits<7:0> of the TBLPAG register and the Effective Address (EA) from a W register specified in the table instruction, as shown in Figure 5-1.

The TBLRDL and TBLWTL instructions are used to read or write to bits<15:0> of program memory. TBLRDL and TBLWTL can access program memory in both Word and Byte modes.

The TBLRDH and TBLWTH instructions are used to read or write to bits<23:16> of program memory. TBLRDH and TBLWTH can also access program memory in Word or Byte mode.

FIGURE 5-1: ADDRESSING FOR TABLE REGISTERS



REGISTER 7-7: IFS2: INTERRUPT FLAG STATUS REGISTER 2

R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
T6IF	DMA4IF	—	OC8IF	OC7IF	OC6IF	OC5IF	IC6IF
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IC5IF	IC4IF	IC3IF	DMA3IF	C1IF	C1RXIF	SPI2IF	SPI2EIF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **T6IF:** Timer6 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 14 **DMA4IF:** DMA Channel 4 Data Transfer Complete Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 13 **Unimplemented:** Read as ‘0’

bit 12 **OC8IF:** Output Compare Channel 8 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 11 **OC7IF:** Output Compare Channel 7 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 10 **OC6IF:** Output Compare Channel 6 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 9 **OC5IF:** Output Compare Channel 5 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 8 **IC6IF:** Input Capture Channel 6 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 7 **IC5IF:** Input Capture Channel 5 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 6 **IC4IF:** Input Capture Channel 4 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 5 **IC3IF:** Input Capture Channel 3 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 4 **DMA3IF:** DMA Channel 3 Data Transfer Complete Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 3 **C1IF:** ECAN1 Event Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

REGISTER 7-12: IEC2: INTERRUPT ENABLE CONTROL REGISTER 2

R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
T6IE	DMA4IE	—	OC8IE	OC7IE	OC6IE	OC5IE	IC6IE
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IC5IE	IC4IE	IC3IE	DMA3IE	C1IE	C1RXIE	SPI2IE	SPI2EIE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **T6IE:** Timer6 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 14 **DMA4IE:** DMA Channel 4 Data Transfer Complete Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 13 **Unimplemented:** Read as '0'

bit 12 **OC8IE:** Output Compare Channel 8 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 11 **OC7IE:** Output Compare Channel 7 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 10 **OC6IE:** Output Compare Channel 6 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 9 **OC5IE:** Output Compare Channel 5 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 8 **IC6IE:** Input Capture Channel 6 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 7 **IC5IE:** Input Capture Channel 5 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 6 **IC4IE:** Input Capture Channel 4 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 5 **IC3IE:** Input Capture Channel 3 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 4 **DMA3IE:** DMA Channel 3 Data Transfer Complete Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 3 **C1IE:** ECAN1 Event Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

REGISTER 7-27: IPC12: INTERRUPT PRIORITY CONTROL REGISTER 12

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	T8IP<2:0>			—	MI2C2IP<2:0>		
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	SI2C2IP<2:0>			—	T7IP<2:0>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **T8IP<2:0>:** Timer8 Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **MI2C2IP<2:0>:** I2C2 Master Events Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **SI2C2IP<2:0>:** I2C2 Slave Events Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **T7IP<2:0>:** Timer7 Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

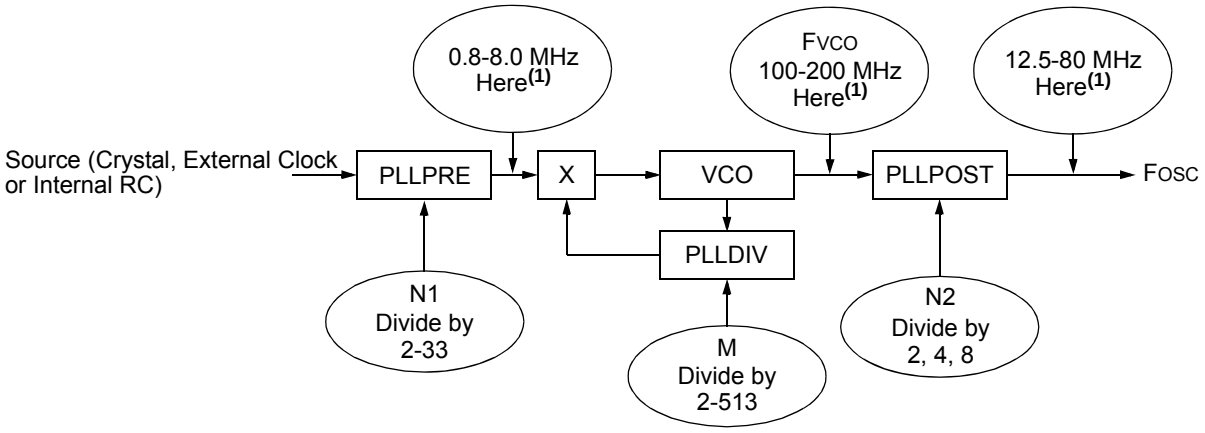
For example, suppose a 10 MHz crystal is being used with “XT with PLL” as the selected oscillator mode. If PLLPRE<4:0> = 0, then N1 = 2. This yields a VCO input of 10/2 = 5 MHz, which is within the acceptable range of 0.8-8 MHz. If PLLDIV<8:0> = 0x1E, then M = 32. This yields a VCO output of 5 * 32 = 160 MHz, which is within the 100-200 MHz ranged needed.

If PLLPOST<1:0> = 0, then N2 = 2. This provides a FOSC of 160/2 = 80 MHz. The resultant device operating speed is 80/2 = 40 MIPS.

EQUATION 9-3: XT WITH PLL MODE EXAMPLE

$$F_{CY} = \frac{F_{OSC}}{2} = \frac{1}{2}\left(\frac{10000000 \cdot 32}{2 \cdot 2}\right) = 40 \text{ MIPS}$$

FIGURE 9-2: dsPIC33FJXXXMCX06A/X08A/X10A PLL BLOCK DIAGRAM



Note 1: This frequency range must be satisfied at all times.

TABLE 9-1: CONFIGURATION BIT VALUES FOR CLOCK SELECTION

Oscillator Mode	Oscillator Source	POSCMD<1:0>	FNOSC<2:0>	See Note
Fast RC Oscillator with Divide-by-N (FRCDIVN)	Internal	xx	111	1, 2
Fast RC Oscillator with Divide-by-16 (FRCDIV16)	Internal	xx	110	1
Low-Power RC Oscillator (LPRC)	Internal	xx	101	1
Secondary (Timer1) Oscillator (Sosc)	Secondary	xx	100	1
Primary Oscillator (HS) with PLL (HSPLL)	Primary	10	011	—
Primary Oscillator (XT) with PLL (XTPLL)	Primary	01	011	—
Primary Oscillator (EC) with PLL (ECPLL)	Primary	00	011	1
Primary Oscillator (HS)	Primary	10	010	—
Primary Oscillator (XT)	Primary	01	010	—
Primary Oscillator (EC)	Primary	00	010	1
Fast RC Oscillator with PLL (FRCPLL)	Internal	xx	001	1
Fast RC Oscillator (FRC)	Internal	xx	000	1

Note 1: OSC2 pin function is determined by the OSCIOFNC Configuration bit.

2: This is the default oscillator mode for an unprogrammed (erased) device.

REGISTER 10-1: PMD1: PERIPHERAL MODULE DISABLE CONTROL REGISTER 1 (CONTINUED)

bit 3 **SPI1MD:** SPI1 Module Disable bit
1 = SPI1 module is disabled
0 = SPI1 module is enabled

bit 2 **C2MD:** ECAN2 Module Disable bit
1 = ECAN2 module is disabled
0 = ECAN2 module is enabled

bit 1 **C1MD:** ECAN1 Module Disable bit
1 = ECAN1 module is disabled
0 = ECAN1 module is enabled

bit 0 **AD1MD:** ADC1 Module Disable bit(1)
1 = ADC1 module is disabled
0 = ADC1 module is enabled

Note 1: The PCFGx bits have no effect if the ADC module is disabled by setting this bit. In this case, all port pins multiplexed with ANx will be in Digital mode.

REGISTER 10-2: PMD2: PERIPHERAL MODULE DISABLE CONTROL REGISTER 2 (CONTINUED)

bit 3 **OC4MD:** Output Compare 4 Module Disable bit
1 = Output Compare 4 module is disabled
0 = Output Compare 4 module is enabled

bit 2 **OC3MD:** Output Compare 3 Module Disable bit
1 = Output Compare 3 module is disabled
0 = Output Compare 3 module is enabled

bit 1 **OC2MD:** Output Compare 2 Module Disable bit
1 = Output Compare 2 module is disabled
0 = Output Compare 2 module is enabled

bit 0 **OC1MD:** Output Compare 1 Module Disable bit
1 = Output Compare 1 module is disabled
0 = Output Compare 1 module is enabled

REGISTER 17-1: QEIxCON: QEIx CONTROL REGISTER

R/W-0	U-0	R/W-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
CNTERR	—	QEISIDL	INDEX	UPDN	QEIM<2:0>		
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SWPAB	PCDOUT	TQGATE	TQCKPS<1:0>		POSRES	TQCS	UPDN_SRC(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CNTERR:** Count Error Status Flag bit
1 = Position count error has occurred
0 = No position count error has occurred
(CNTERR flag only applies when QEIM<2:0> = '110' or '100')

bit 14 **Unimplemented:** Read as '0'

bit 13 **QEISIDL:** Stop in Idle Mode bit
1 = Discontinue module operation when device enters Idle mode
0 = Continue module operation in Idle mode

bit 12 **INDEX:** Index Pin State Status bit (read-only)
1 = Index pin is High
0 = Index pin is Low

bit 11 **UPDN:** Position Counter Direction Status bit
1 = Position counter direction is positive (+)
0 = Position counter direction is negative (-)
(Read-only bit when QEIM<2:0> = '1xx'. Read/write bit when QEIM<2:0> = 001.)

bit 10-8 **QEIM<2:0>:** Quadrature Encoder Interface Mode Select bits
111 = Quadrature Encoder Interface enabled (x4 mode) with Position Counter Reset by match (MAXCNT)
110 = Quadrature Encoder Interface enabled (x4 mode) with Index Pulse Reset of position counter
101 = Quadrature Encoder Interface enabled (x2 mode) with Position Counter Reset by match (MAXCNT)
100 = Quadrature Encoder Interface enabled (x2 mode) with Index Pulse Reset of position counter
011 = Unused (module disabled)
010 = Unused (module disabled)
001 = Starts 16-bit Timer
000 = Quadrature Encoder Interface/timer off

bit 7 **SWPAB:** Phase A and Phase B Input Swap Select bit
1 = Phase A and Phase B inputs swapped
0 = Phase A and Phase B inputs not swapped

bit 6 **PCDOUT:** Position Counter Direction State Output Enable bit
1 = Position counter direction status output enable (QEI logic controls state of I/O pin)
0 = Position counter direction status output disabled (normal I/O pin operation)

bit 5 **TQGATE:** Timer Gated Time Accumulation Enable bit
1 = Timer gated time accumulation enabled
0 = Timer gated time accumulation disabled

Note 1: When configured for QEI mode, the control bit is a 'don't care'.

REGISTER 19-1: I2CxCON: I2Cx CONTROL REGISTER (CONTINUED)

bit 5 **ACKDT:** Acknowledge Data bit (when operating as I^2C master, applicable during master receive)
Value that will be transmitted when the software initiates an Acknowledge sequence.
1 = Send NACK during Acknowledge
0 = Send ACK during Acknowledge

bit 4 **ACKEN:** Acknowledge Sequence Enable bit
(when operating as I^2C master, applicable during master receive)
1 = Initiate Acknowledge sequence on SDAx and SCLx pins and transmit ACKDT data bit. Hardware clear at end of master Acknowledge sequence
0 = Acknowledge sequence not in progress

bit 3 **RCEN:** Receive Enable bit (when operating as I^2C master)
1 = Enables Receive mode for I^2C. Hardware clear at end of eighth bit of master receive data byte
0 = Receive sequence not in progress

bit 2 **PEN:** Stop Condition Enable bit (when operating as I^2C master)
1 = Initiate Stop condition on SDAx and SCLx pins. Hardware clear at end of master Stop sequence
0 = Stop condition not in progress

bit 1 **RSEN:** Repeated Start Condition Enable bit (when operating as I^2C master)
1 = Initiate Repeated Start condition on SDAx and SCLx pins. Hardware clear at end of master Repeated Start sequence
0 = Repeated Start condition not in progress

bit 0 **SEN:** Start Condition Enable bit (when operating as I^2C master)
1 = Initiate Start condition on SDAx and SCLx pins. Hardware clear at end of master Start sequence
0 = Start condition not in progress

REGISTER 21-5: CiFIFO: ECAN™ FIFO STATUS REGISTER

U-0	U-0	R-0	R-0	R-0	R-0	R-0	R-0
—	—	FBP<5:0>					
bit 15							bit 8

U-0	U-0	R-0	R-0	R-0	R-0	R-0	R-0
—	—	FNRB<5:0>					
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-8 **FBP<5:0>:** FIFO Write Buffer Pointer bits
011111 = RB31 buffer
011110 = RB30 buffer
•
•
•
000001 = TRB1 buffer
000000 = TRB0 buffer

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **FNRB<5:0>:** FIFO Next Read Buffer Pointer bits
011111 = RB31 buffer
011110 = RB30 buffer
•
•
•
000001 = TRB1 buffer
000000 = TRB0 buffer

REGISTER 21-24: CiRXOVF1: ECAN™ RECEIVE BUFFER OVERFLOW REGISTER 1

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXOVF15	RXOVF14	RXOVF13	RXOVF12	RXOVF11	RXOVF10	RXOVF9	RXOVF8
bit 15							bit 8

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXOVF7	RXOVF6	RXOVF5	RXOVF4	RXOVF3	RXOVF2	RXOVF1	RXOVF0
bit 7							bit 0

Legend:		C= Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **RXOVF15:RXOVF0:** Receive Buffer n Overflow bits
1 = Module pointed a write to a full buffer (set by module)
0 = Overflow is cleared (clear by application software)

REGISTER 21-25: CiRXOVF2: ECAN™ RECEIVE BUFFER OVERFLOW REGISTER 2

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXOVF31	RXOVF30	RXOVF29	RXOVF28	RXOVF27	RXOVF26	RXOVF25	RXOVF24
bit 15							bit 8

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXOVF23	RXOVF22	RXOVF21	RXOVF20	RXOVF19	RXOVF18	RXOVF17	RXOVF16
bit 7							bit 0

Legend:		C= Clearable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **RXOVF31:RXOVF16:** Receive Buffer n Overflow bits
1 = Module pointed a write to a full buffer (set by module)
0 = Overflow is cleared (clear by application software)

TABLE 26-21: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SY10	TMCL	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	μs	-40°C to +85°C
SY11	TPWRT	Power-up Timer Period	— — — — — — —	2 4 8 16 32 64 128	— — — — — — —	ms	-40°C to +85°C User programmable
SY12	TPOR	Power-on Reset Delay	3	10	30	μs	-40°C to +85°C
SY13	TIOZ	I/O High-Impedance from $\overline{\text{MCLR}}$ Low or Watchdog Timer Reset	0.68	0.72	1.2	μs	—
SY20	TWDT1	Watchdog Timer Time-out Period	—	—	—	—	See **Section 23.4 "Watchdog Timer (WDT)"** and LPRC specification F21 (Table 26-19)
SY30	TOST	Oscillator Start-up Timer Period	—	1024 TOSC	—	—	TOSC = OSC1 period
SY35	TFSCM	Fail-Safe Clock Monitor Delay	—	500	900	μs	-40°C to +85°C

Note 1: These parameters are characterized but not tested in manufacturing.
2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

FIGURE 26-11: QEA/QEB INPUT CHARACTERISTICS

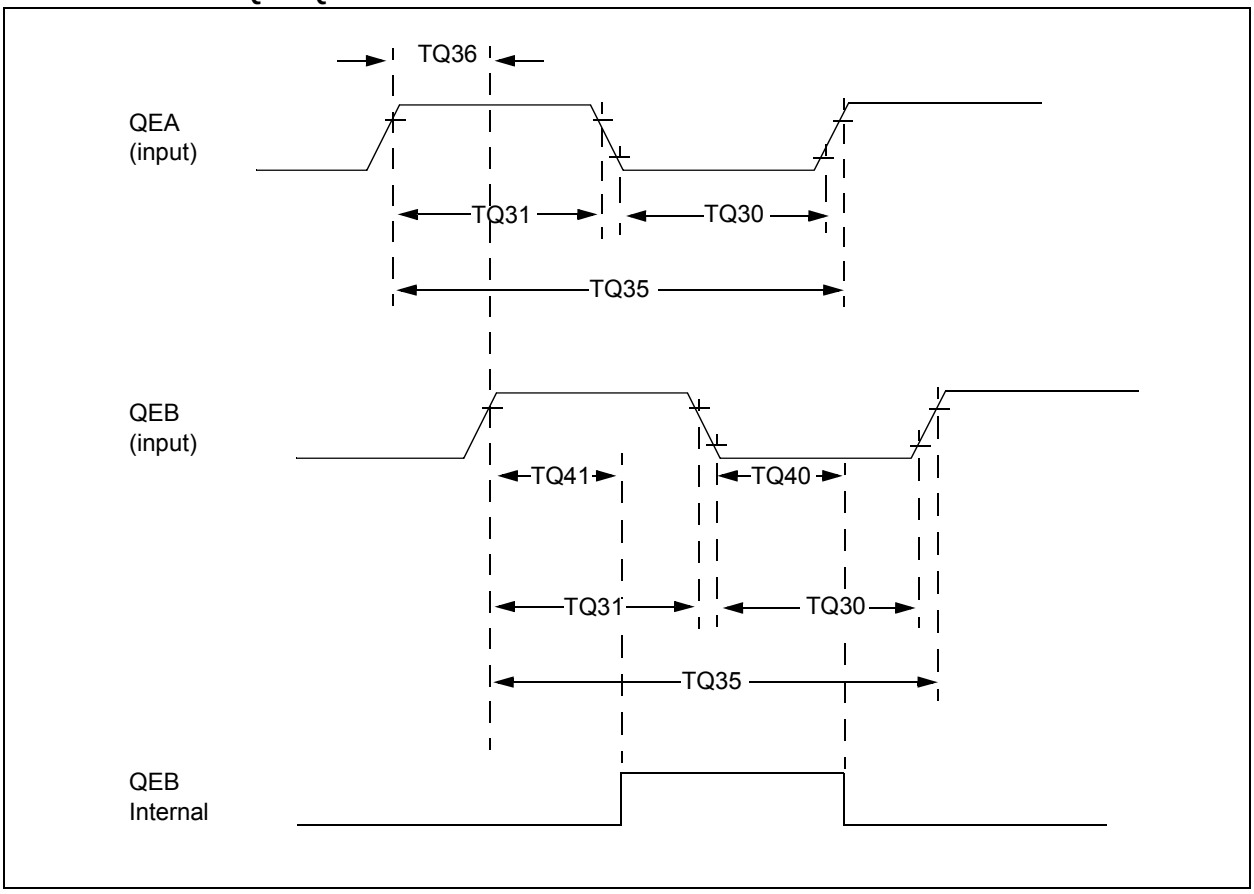


TABLE 26-29: QUADRATURE DECODER TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic(1)**	**Typ(2)**	**Max**	**Units**	**Conditions**
TQ30	TQUL	Quadrature Input Low Time	6 TCY	—	ns	—
TQ31	TQUH	Quadrature Input High Time	6 TCY	—	ns	—
TQ35	TQUIN	Quadrature Input Period	12 TCY	—	ns	—
TQ36	TQUP	Quadrature Phase Period	3 TCY	—	ns	—
TQ40	TQUFL	Filter Time to Recognize Low with Digital Filter	3 * N * TCY	—	ns	N = 1, 2, 4, 16, 32, 64, 128 and 256 **(Note 3)**
TQ41	TQUFH	Filter Time to Recognize High with Digital Filter	3 * N * TCY	—	ns	N = 1, 2, 4, 16, 32, 64, 128 and 256 **(Note 3)**

Note 1: These parameters are characterized but not tested in manufacturing.

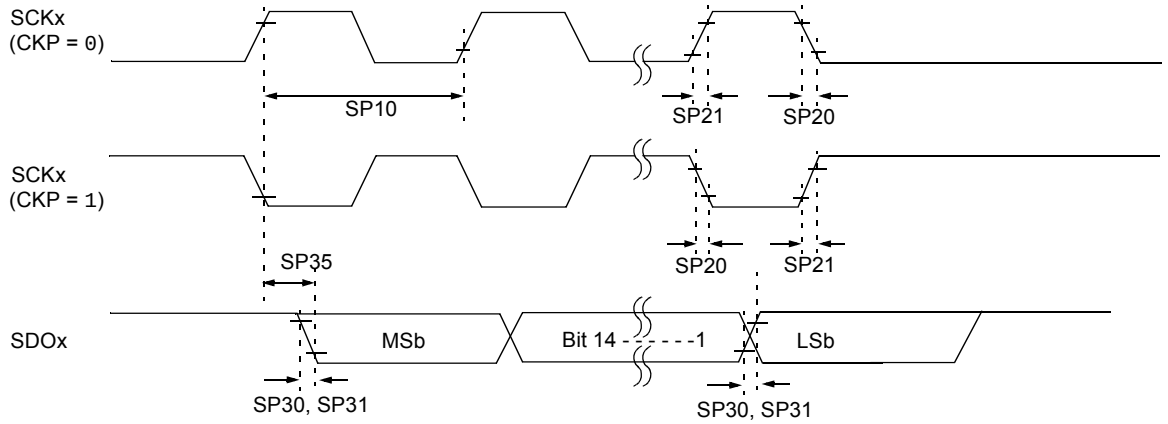
2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

3: N = Index Channel Digital Filter Clock Divide Select bits. Refer to **Section 15. "Quadrature Encoder Interface (QEI)"** (DS70208) in the "*dsPIC33F/PIC24H Family Reference Manual*".

TABLE 26-32: SPIx MAXIMUM DATA/CLOCK RATE SUMMARY

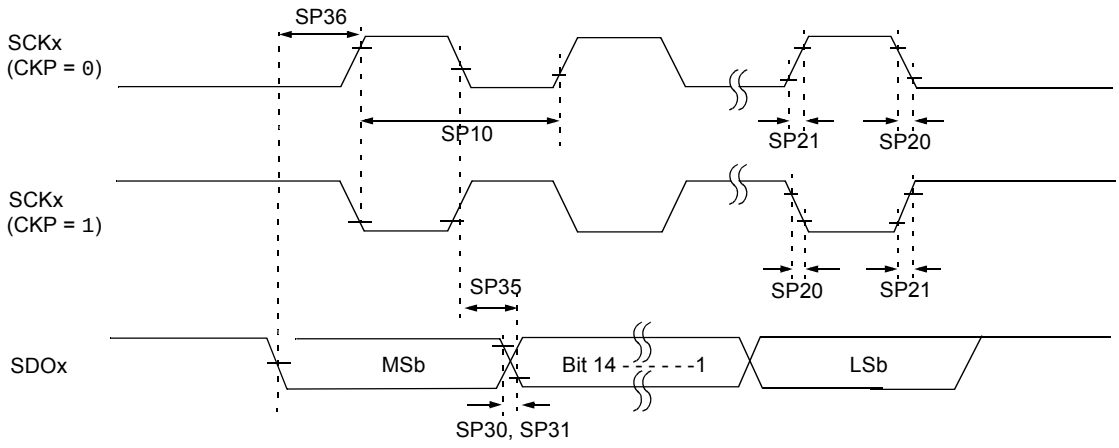
AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Maximum Data Rate	**Master Transmit Only (Half-Duplex)**	**Master Transmit/Receive (Full-Duplex)**	**Slave Transmit/Receive (Full-Duplex)**	**CKE**	**CKP**	**SMP**
15 MHz	Table 26-33	—	—	0,1	0,1	0,1
10 MHz	—	Table 26-34	—	1	0,1	1
10 MHz	—	Table 26-35	—	0	0,1	1
15 MHz	—	—	Table 26-36	1	0	0
11 MHz	—	—	Table 26-37	1	1	0
15 MHz	—	—	Table 26-38	0	1	0
11 MHz	—	—	Table 26-39	0	0	0

FIGURE 26-14: SPIx MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 26-1 for load conditions.

FIGURE 26-15: SPIx MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 26-1 for load conditions.

FIGURE 26-21: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING CHARACTERISTICS

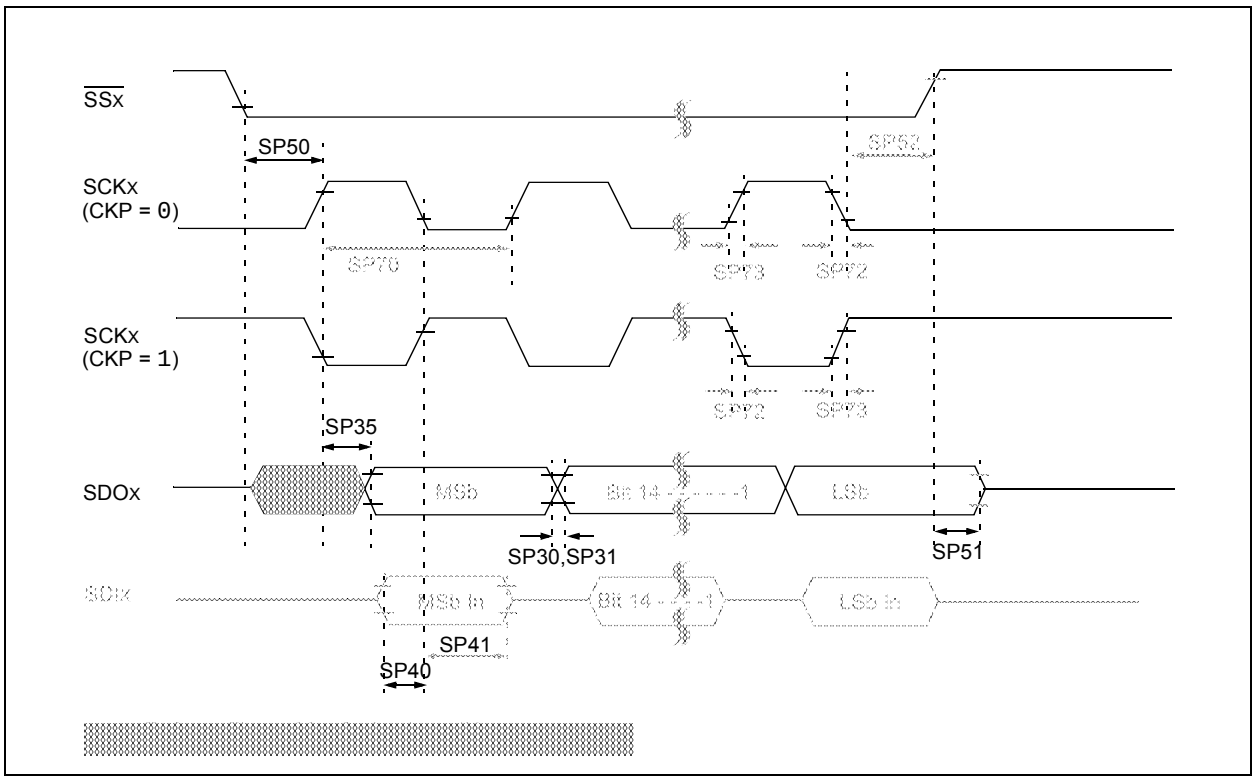


TABLE 26-40: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic**		**Min(1)**	**Max**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	—
IM11	THI:SCL	Clock High Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	—
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode(2)	40	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	µs	—
			400 kHz mode	0	0.9	µs	
			1 MHz mode(2)	0.2	—	µs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	After this period the first clock pulse is generated
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	ns	—
			400 kHz mode	TCY/2 (BRG + 1)	—	ns	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	ns	
IM40	TAA:SCL	Output Valid From Clock	100 kHz mode	—	3500	µs	—
			400 kHz mode	—	1000	µs	—
			1 MHz mode(2)	—	400	µs	—
IM45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
			1 MHz mode(2)	0.5	—	µs	
IM50	CB	Bus Capacitive Loading		—	400	pF	—
IM51	TPGD	Pulse Gobbler Delay		65	390	ns	**See Note 3**

Note 1: BRG is the value of the I2C™ Baud Rate Generator. Refer to **Section 19. "Inter-Integrated Circuit (I2C™)"** (DS70195) in the "*dsPIC33F/PIC24H Family Reference Manual*".

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: Typical value for this parameter is 130 ns.

TABLE 26-46: ADC CONVERSION (12-BIT MODE) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ**	**Max.**	**Units**	**Conditions**
Clock Parameters							
AD50a	TAD	ADC Clock Period	117.6	—	—	ns	—
AD51a	tRC	ADC Internal RC Oscillator Period	—	250	—	ns	—
Conversion Rate							
AD55a	tCONV	Conversion Time	—	14 TAD		—	—
AD56a	FCNV	Throughput Rate	—	—	500	ksps	—
AD57a	TSAMP	Sample Time	3.0 TAD	—	—	—	—
Timing Parameters							
AD60a	tPCS	Conversion Start from Sample Trigger(1,2)	2.0 TAD	—	3.0 TAD	—	—
AD61a	tPSS	Sample Start from Setting Sample (SAMP) bit(1,2)	2.0 TAD	—	3.0 TAD	—	—
AD62a	tCSS	Conversion Completion to Sample Start (ASAM = 1)(1,2)	—	0.5 TAD	—	—	—
AD63a	tDPU	Time to Stabilize Analog Stage from ADC Off to ADC On(1,2,3)	—	—	20	μs	—

Note 1: Because the sample caps will eventually lose charge, clock rates below 10 kHz can affect linearity performance, especially at elevated temperatures.

2: These parameters are characterized but not tested in manufacturing.

3: tDPU is the time required for the ADC module to stabilize when it is turned on (AD1CON1<ADON> = 1). During this time, the ADC result is indeterminate.

TABLE 27-6: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for High Temperature				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
HDO10	VOL	**Output Low Voltage** I/O Pins: 2x Sink Driver Pins - All pins not defined by 4x or 8x driver pins	—	—	0.4	V	IOL ≤ 1.8 mA, VDD = 3.3V See **Note 1**
		Output Low Voltage I/O Pins: 4x Sink Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	—	—	0.4	V	IOL ≤ 3.6 mA, VDD = 3.3V See **Note 1**
		Output Low Voltage I/O Pins: 8x Sink Driver Pins - OSC2, CLKO, RC15	—	—	0.4	V	IOL ≤ 6 mA, VDD = 3.3V See **Note 1**
HDO20	VOH	**Output High Voltage** I/O Pins: 2x Source Driver Pins - All pins not defined by 4x or 8x driver pins	2.4	—	—	V	IOL ≥ -1.8 mA, VDD = 3.3V See **Note 1**
		Output High Voltage I/O Pins: 4x Source Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	2.4	—	—	V	IOL ≥ -3 mA, VDD = 3.3V See **Note 1**
		Output High Voltage I/O Pins: 8x Source Driver Pins - OSC2, CLKO, RC15	2.4	—	—	V	IOL ≥ -6 mA, VDD = 3.3V See **Note 1**
HDO20A	VOH1	**Output High Voltage** I/O Pins: 2x Source Driver Pins - All pins not defined by 4x or 8x driver pins	1.5	—	—	V	IOH ≥ -1.9 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -1.85 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -1.4 mA, VDD = 3.3V See **Note 1**
		Output High Voltage 4x Source Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	1.5	—	—	V	IOH ≥ -3.9 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -3.7 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -2 mA, VDD = 3.3V See **Note 1**
		Output High Voltage 8x Source Driver Pins - OSC2, CLKO, RC15	1.5	—	—	V	IOH ≥ -7.5 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -6.8 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -3 mA, VDD = 3.3V See **Note 1**

Note 1: Parameters are characterized, but not tested.